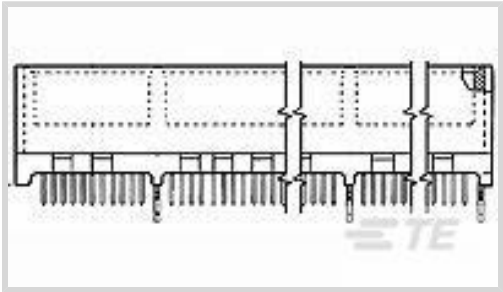




Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



EU RoHS Compliance: **Compliant**

EU ELV Compliance: **Compliant**

Connector System: **Board-to-Board**

Contact Mating Area Plating Material Thickness: **[ 30 µin ]**

Number of Positions: **184**

Features

Other

|                    |           |
|--------------------|-----------|
| EU RoHS Compliance | Compliant |
| EU ELV Compliance  | Compliant |

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System                  | Board-to-Board        |

Configuration Features

|                                        |          |
|----------------------------------------|----------|
| Number of PCB Mount Retention Features | 3        |
| Number of Positions                    | 184      |
| PCB Mount Orientation                  | Vertical |
| Ejector                                | Without  |

Electrical Characteristics

|                   |         |
|-------------------|---------|
| Operating Voltage | 203 VAC |
|-------------------|---------|

Body Features

|                                        |         |
|----------------------------------------|---------|
| PCB Retention Feature Material         | Brass   |
| PCB Retention Feature Plating Material | Tin     |
| Product Weight                         | 17.65 g |
| Primary Product Color                  | Natural |

Contact Features

|                                                         |          |
|---------------------------------------------------------|----------|
| PCB Contact Termination Area Plating Material Thickness | 2.537 µm |
|---------------------------------------------------------|----------|



|                                               |                 |
|-----------------------------------------------|-----------------|
| Contact Underplating Material                 | Nickel          |
| Contact Mating Area Plating Material          | Gold            |
| Contact Base Material                         | Phosphor Bronze |
| PCB Contact Termination Area Plating Material | Tin             |
|                                               | 30 µin          |

Termination Features

|                                |                       |
|--------------------------------|-----------------------|
| Termination Method to PCB      | Through Hole - Solder |
| Termination Post & Tail Length | 2.54 mm[.1 in]        |

Mechanical Attachment

|                          |                |
|--------------------------|----------------|
| Connector Mounting Type  | Board Mount    |
| PCB Mount Retention Type | Hold-Down Post |

Housing Features

|                    |                                |
|--------------------|--------------------------------|
| Housing Material   | High Temperature Thermoplastic |
| Centerline (Pitch) | 1.27 mm[.05 in]                |

Dimensions

|                          |                  |
|--------------------------|------------------|
| PCB Thickness (Accepted) | 1.57 mm[.062 in] |
| Connector Length         | 128 mm[5.039 in] |
| Connector Height         | 13.97 mm[.55 in] |
| Connector Width          | 8.88 mm[.35 in]  |

Usage Conditions

|                             |                           |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

|          |     |
|----------|-----|
| Bus Type | PCI |
|----------|-----|

Packaging Features

|                    |     |
|--------------------|-----|
| Packaging Method   | Box |
| Packaging Quantity | 35  |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                              |           |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|



|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2024 (241)<br>Candidate List Declared Against: JUNE 2024 (241)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                  |
| Solder Process Capability                     | Wave solder capable to 265°C                                                                                                    |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



TE Part # 5145154-1  
CONNECTOR, 60 DUAL POSITION, .

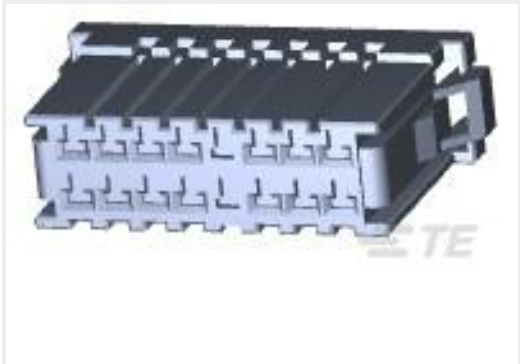


TE Part # 5-2337939-4  
PCIE GEN4 CON,SMT,164POS,30u", MYLAR,HT



TE Part # 1734774-1  
PCI EXP 3.1L 36 POS WHT G/F

Customers Also Bought



TE Part #178289-7  
DYNAMIC D3100 REC HSG 16P



TE Part #9-188275-0  
MICRO-MATCH SMD FTE



TE Part #1-1879417-5  
CPF 0603 680K 0.1% 25PPM 1K RL



TE Part #4-1393222-6  
V23061A1007A502=MINISTARKSTROM



Documents

Product Drawings

STANDARD EDGE .050 SERIES 92 DUAL ASSY

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_5145168-4\_D.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_5145168-4\_D.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_5145168-4\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English